SMD0805 Series

ROHS

Surface Mount Resettable PTCs

Description

The SMD0805 Series PTC provides surface mount over-current protection for applications where space is at a premium and reset table protection is desired.

Features

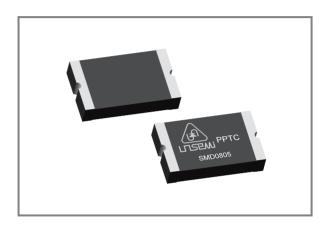
- ◆ RoHS compliant, Lead-Free and Halogen-Free
- ◆ Faster tripping, 0805 Dimension
- ◆ Compact design saves board space
- ◆ Compatible with high temperature solders
- Agency recognition: UL
- ◆ Low-profile

Applicable

- Battery PCM
- ◆ PDAs & Charger, Analog & digital line card
- Digital cameras
- ◆ General electronics
- USB peripherals
- Power ports

L D STP Mi

www.unsemi.com.tw



Electrical Parameters

Doub Name on	Mankina	I hold	l trip	V max	I max	Pdtyp.		ım Time Trip	Resis	tance
Part Number	Marking	(A)	(A)	(Vdc)	(A)	(W)	Current (A)	Time (Sec.)	R min (Ω)	R 1max (Ω)
SMD0805-005	1	0.05	0.15	24	100	0.5	0.50	1.50	1.50	20.00
SMD0805-010	1	0.10	0.30	15	100	0.5	0.50	1.50	1.00	6.00
SMD0805-010/24V	1	0.10	0.30	24	100	0.5	0.50	1.50	1.00	8.00
SMD0805-020	2	0.20	0.50	9	100	0.5	8.00	0.02	0.50	3.50
SMD0805-025	2	0.25	0.50	6	100	0.5	8.00	0.02	0.45	3.20
SMD0805-030	3	0.30	0.70	6	100	0.5	8.00	0.10	0.25	2.00
SMD0805-035	3	0.35	0.75	6	100	0.5	8.00	0.10	0.25	1.20
SMD0805-050	5	0.50	1.00	6	100	0.6	8.00	0.10	0.15	0.85
SMD0805-075	7	0.75	1.50	6	100	0.6	8.00	0.20	0.09	0.385
SMD0805-100	0	1.00	1.95	6	100	0.6	8.00	0.30	0.06	0.23
SMD0805-110	0	1.10	2.20	6	100	0.6	8.00	0.30	0.06	0.21

I hold= Hold current: maximum current device will pass without tripping in 25°C still air.

I trip= Trip current: minimum current at which the device will trip in 25°C still air.

V max= Maximum voltage device can withstand without damage at rated current (Imax)

I max= Maximum fault current device can withstand without damage at rated voltage (Vmax)

Pdtyp.= Power dissipated from device when in the tripped state at 25°C still air.

R min= Minimum resistance of device in initial (un-soldered) state.

R max= Maximum resistance of device in initial (un-soldered) state.

R 1max= Maximum resistance of device at 25°C measured one hour after tripping.



ROHS

Temperature Rerating Chart – I hold (A)

		Ambient Operation Temperature							
Part Number	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
				Hold Cur	rent (A)				
SM0805-005	0.070	0.063	0.058	0.050	0.043	0.035	0.030	0.025	0.018
SMD0805-010	0.140	0.125	0.115	0.100	0.085	0.070	0.060	0.050	0.035
SMD0805-010/24V	0.140	0.125	0.115	0.100	0.085	0.070	0.060	0.050	0.035
SMD0805-020	0.280	0.250	0.230	0.200	0.170	0.140	0.120	0.100	0.070
SMD0805-025	0.350	0.310	0.290	0.250	0.210	0.180	0.150	0.013	0.090
SMD0805-030	0.420	0.380	0.350	0.300	0.255	0.210	0.180	0.150	0.110
SMD0805-035	0.470	0.440	0.390	0.350	0.300	0.270	0.240	0.200	0.140
SMD0805-050	0.680	0.620	0.550	0.500	0.400	0.370	0.330	0.290	0.230
SMD0805-075	1.000	0.900	0.790	0.750	0.630	0.570	0.530	0.410	0.340
SMD0805-100	1.350	1.250	1.100	1.000	0.820	0.740	0.650	0.550	0.420
SMD0805-110	1.450	1.350	1.200	1.100	0.920	0.840	0.750	0.650	0.520

Test Procedures and Requirement

Test Item	Test Conditions	Accept/Reject Criteria
Initial Resistance	In still air at 25°C	RMIN ≤ R ≤ R1MAX
Time to Trip	Specified current, VMAX, 25°C	T ≤ Maximum Time to Trip
Hold Current	30min, at IH, 25°C	No trip
Trip Cycle Life	VMAX, Imax, 100cycles	No arcing or burning
Trip Endurance	VMAX, 1 hour	No arcing or burning

Physical Characteristics

Terminal Materials	Tin-Plated Nickle-copper
Soldering Zone	Meets EIA specification RS 186-9E and ANSI/J-STD-002 Category 3.

Environmental Specifications

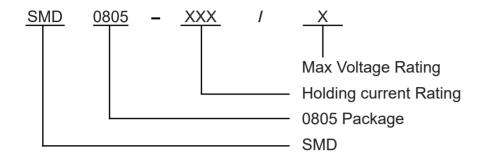
Test Item	Test Conditions	Resistance Change
Passive Aging	85°C ,1000 hours	±10% typical
Humidity Aging	85°C/85%RH.1000 hours	±5% typical
Thermal Shock	MIL-STD-202,Method 107G +85 °C/-40°C ,20 times	-30% typical
Solvent Resistance	MIL-STD-202,Method 215	No change
Vibration	ML-STD-883C,Test Condition A	No change

Specifications are subject to change without notice. Please refer to www.unsemi.com.tw for current information.

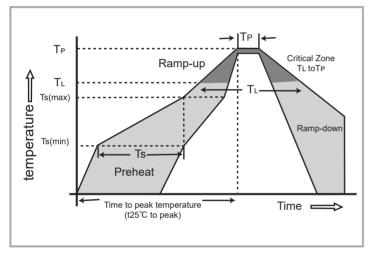


ROHS

Part Numbering System



Soldering Parameters



- Recommended reflow methods: IR, vapor phase oven, hot air oven, N2 environment for lead-free.
- Devices are not designed to be wave soldered to the bottom side of the board.
- ◆ Recommended maximum paste thickness is 0.25mm (0.010inch).
- Devices can be cleaned using standard industry methods and solvents.
- Soldering temperature profile meets RoHs lead free process.
 Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements

Reflow	Condition	Lead–free assembly	
	-Temperature Min (Ts _(min))	150°C	
Pre Heat	-Temperature Max (Ts _(max))	200°C	
	- Time (min to max) (Ts)	60 -120 Seconds	
	e ramp up rate (Liquidus L) to peak	3°C/second max	
Ts(max) to TL - Ramp-up Rate		3°C/second max	
Reflow	- Temperature (TL) (Liquidus)	217°C	
Renow	- Time (min to max) (Ts)	60 -150 Seconds	
Peak Te	mperature (TP)	260 +0/-5°C	
	thin 5°C of actual peak ature (TP)	30 Seconds	
Ramp-d	lown Rate	3°C/second max	
Time 25	°C to peak Temperature (TP)	8 minutes Max	
Do not	exceed	260°C	

Caution:

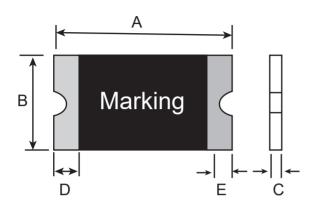
- 1. If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements
- 2. Operation beyond the specified rating may result in damage and possible arcing and flame.
- 3. PPTC are intended for protection against occasional over current or over temperature fault conditions and should not be used when repeated fault conditions or prolonged trip events are anticipated.

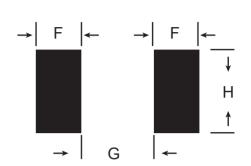




ROHS

Dimensions Unit: mm





	,	Ą	I	3		С	D	Е
Part Number	Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.
SMD0805-005	2.00	2.20	1.20	1.50	0.45	1.00	0.20	0.10
SMD0805-010	2.00	2.20	1.20	1.50	0.40	1.00	0.20	0.10
SMD0805-010/24V	2.00	2.20	1.20	1.50	0.50	1.00	0.20	0.10
SMD0805-020	2.00	2.20	1.20	1.50	0.40	1.00	0.20	0.10
SMD0805-025	2.00	2.20	1.20	1.50	0.40	1.00	0.20	0.10
SMD0805-030	2.00	2.20	1.20	1.50	0.30	1.00	0.20	0.10
SMD0805-035	2.00	2.20	1.20	1.50	0.30	1.00	0.20	0.10
SMD0805-050	2.00	2.20	1.20	1.50	0.40	0.80	0.20	0.10
SMD0805-075	2.00	2.20	1.20	1.50	0.50	1.20	0.20	0.10
SMD0805-100	2.00	2.20	1.20	1.50	0.50	1.20	0.20	0.10
SMD0805-110	2.00	2.20	1.20	1.50	0.50	1.20	0.20	0.10

Layout Dimensions Unit: mm

Part Number	F	G	Н	
i ait number	Normal Value	Normal Value	Normal Value	
SMD0805 Series	1.0±0.1	1.2±0.1	1.5±0.1	



ROHS

Ordering Information

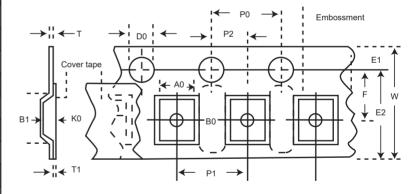
Part Number	Quantity
SMD0805-005	5,000 pcs/Reel
SMD0805-010	5,000 pcs/Reel
SMD0805-010/24V	5,000 pcs/Reel
SMD0805-020	5,000 pcs/Reel
SMD0805-025	5,000 pcs/Reel
SMD0805-030	5,000 pcs/Reel
SMD0805-035	5,000 pcs/Reel
SMD0805-050	5,000 pcs/Reel
SMD0805-075	4,000 pcs/Reel
SMD0805-100	4,000 pcs/Reel
SMD0805-110	4,000 pcs/Reel

Tape Specification and Reel Specifications

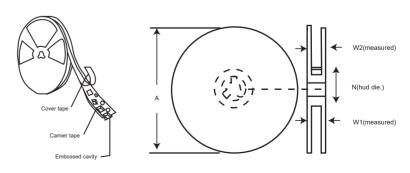
Coverning Specifications EIA 481-1(Unit:mm)				
W	8.00±0.10			
P0	4.00±0.10			
P1	4.00±0.10			
P2	2.00±0.05			
A0	0.95±0.10			
В0	1.85±0.10			
D0	1.55±0.05			
F	3.50±0.05			
E1	1.75±0.10			
Т	0.20±0.02			
Leader min.	390			
Traile min.	160			

Reel Dimensions					
Α	178±1.0				
N	59±1.0				
W1	8.5 + 1.0/-0.2				
W2	12.0±1.0				

ELA Tape Component Dimentions



EIA Reel Dimentions





ROHS

Disclaimer

UNSEMI RESERVES THE RIGHT TO MAKE CHANGE ON OUR PRODUTS, PRODUCTS SPECIFICATION AND DATA WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

UN SEMICONDUCTOR LIMITED its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "UNSEMI")does not give any representations or warranties for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

In no event shall UNSEMI be liable for any indirect, incidental, punitive, special or consequential damages (including any and all implied warranties, warranties of fitness for particular purpose, non-infringement and merchantability.) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Statements regarding the suitability of products for certain types of applications are based on UNSEMI knowledge of typical requirements that are often placed on UNSEMI products in generic applications. Such statements are not binding, statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify UNSEMI's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Unless otherwise agreed in writing, UNSEMI product is not designed, authorized or warranted to be suitable for use in medical life-saving, or life-sustaining application, nor in applications where failure or malfunction of a UNSEMI product can reasonably be expected to result in personal injury, death or severe property or environmental damage. UNSEMI and its suppliers accept no liability for inclusion or use of UNSEMI products in such equipment or applications and therefore such inclusion and/or use is at the customer's own risk.

All referenced brands, product names, service names and trademarks are the property of their respective owners.